L Number	Hits	Search Text	DB	Time stamp
-	194506	TAB or (tape near3 automate near3 bonding)	USPAT;	2004/07/23 16:05
			US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
-	256146	TAB or (tape near3 automate near3 bonding)	USPĀT;	2004/07/23 16:05
			US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
_	256143	TAB or (tape near3 automate near3 bonding) with (CSP (chip near size	USPAT;	2004/07/23 16:08
		near package) cof (chip adj on adj film) BGA (ball near grid near array))	US-PGPUB;	
		hear passinger our (strip and on any minit) best (sum near gird near array))	ЕРО; ЛРО;	
			DERWENT;	
			IBM TDB	
_	282561	TAB or (tape near3 automate near3 bonding) or (CSP (chip near size	USPAT;	2004/07/23 16:14
_	202501	near package) cof (chip adj on adj film) BGA (ball near grid near array))	US-PGPUB;	2004/07/25 10:14
		hear package, our (emp auj on auj min, bort (ban hear gnu hear allay))	ЕРО; ЛРО;	
			DERWENT;	
•			IBM_TDB	
	811	(TAB or (tape near3 automate near3 bonding) or (CSP (chip near size	USPAT;	2004/07/28 15:27
-	611	near package) cof (chip adj on adj film) BGA (ball near grid near		2004/07/28 13.27
			US-PGPUB;	
		array))) with film near3 carrier	ЕРО; ЛРО;	
			DERWENT;	
	501	(cond-m402 m2 1)	IBM_TDB	2004/07/22 16:11
-	521	(undercoat\$3 near2 layer) with (nickel Ni)	USPAT;	2004/07/23 16:11
			US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
	5000		IBM_TDB	2004/07/22 16 12
-	5890	intermediate with (palladium Pd)	USPAT;	2004/07/23 16:12
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1	((TAB or (tape near3 automate near3 bonding) or (CSP (chip near size	IBM_TDB USPAT;	2004/07/23 16:12
-	1	near package) cof (chip adj on adj film) BGA (ball near grid near		2004/07/23 10.12
1			US-PGPUB;	
		array))) with film near3 carrier) and ((undercoat\$3 near2 layer) with	EPO; JPO;	
1		(nickel Ni))	DERWENT;	
	4	((undercoat\$3 near2 layer) with (nickel Ni)) and (intermediate with	IBM_TDB	2004/07/22 16:17
-	4	((undercoats) hearz layer) with (nickel N1) ) and (intermediate with (palladium Pd))	USPAT;	2004/07/23 16:17
		(Panadium Fu))	US-PGPUB;	
			EPO; JPO;	
]			DERWENT;	
[	011	(TAR or (tane near) automate near) handing) or (CSR (ship near size	IBM_TDB	2004/07/22 16:15
-	811	(TAB or (tape near3 automate near3 bonding) or (CSP (chip near size	USPAT;	2004/07/23 16:15
		near package) cof (chip adj on adj film) BGA (ball near grid near	US-PGPUB;	
		array))) and ((TAB or (tape near3 automate near3 bonding) or (CSP	ЕРО; ЛРО;	
		(chip near size near package) cof (chip adj on adj film) BGA (ball near	DERWENT;	
		grid near array))) with film near3 carrier)	IBM_TDB	0004/07/07
-	1	((TAB or (tape near3 automate near3 bonding) or (CSP (chip near size	USPAT;	2004/07/23 16:15
]		near package) cof (chip adj on adj film) BGA (ball near grid near	US-PGPUB;	
j		array))) and ((TAB or (tape near3 automate near3 bonding) or (CSP	ЕРО; ЈРО;	
		(chip near size near package) cof (chip adj on adj film) BGA (ball near	DERWENT;	
		grid near array))) with film near3 carrier)) and ((undercoat\$3 near2	IBM_TDB	
ļ		layer) with (nickel Ni))		
-	2750	(TAB or (tape near3 automate near3 bonding) or (CSP (chip near size	USPAT;	2004/07/23 16:18
		near package) cof (chip adj on adj film) BGA (ball near grid near	US-PGPUB;	
		array))) and layer near3 (nickel Ni)	ЕРО; ЛРО;	
			DERWENT;	
		<u> </u>	IBM_TDB	

-	2079	((TAB or (tape near3 automate near3 bonding) or (CSP (chip near size near package) cof (chip adj on adj film) BGA (ball near grid near	USPAT; US-PGPUB;	2004/07/23 16:19
		array))) and layer near3 (nickel Ni)) and (gold Au)	EPO; JPO; DERWENT; IBM_TDB	
-	885	(((TAB or (tape near3 automate near3 bonding) or (CSP (chip near size near package) cof (chip adj on adj film) BGA (ball near grid near	USPAT; US-PGPUB;	2004/07/23 16:27
		array))) and layer near3 (nickel Ni)) and (gold Au)) and (palladium Pd)	EPO; JPO; DERWENT;	
-	395	((((TAB or (tape near3 automate near3 bonding) or (CSP (chip near size	IBM_TDB USPAT;	2004/07/23 16:28
:		near package) cof (chip adj on adj film) BGA (ball near grid near array))) and layer near3 (nickel Ni)) and (gold Au)) and (palladium Pd)) and bond\$3 adj pad	US-PGPUB; EPO; JPO; DERWENT;	
-	99	(bond\$3 adj pad) with (nickel Ni) with (palladium Pd)	IBM_TDB USPAT;	2004/07/23 16:31
			US-PGPUB; EPO; JPO; DERWENT;	
-	54	(TAB or (tape near3 automate near3 bonding) or (CSP (chip near size	IBM_TDB USPAT;	2004/07/28 16:51
		near package) cof (chip adj on adj film) BGA (ball near grid near array))) and ((bond\$3 adj pad) with (nickel Ni) with (palladium Pd))	US-PGPUB; EPO; JPO; DERWENT;	
-	3	((TAB or (tape near3 automate near3 bonding) or (CSP (chip near size	IBM_TDB USPAT;	2004/07/23 16:32
		near package) cof (chip adj on adj film) BGA (ball near grid near array))) and ((bond\$3 adj pad) with (nickel Ni) with (palladium Pd))) and film near3 carrier	US-PGPUB; EPO; JPO; DERWENT;	
-	14494	(copper Cu) with (nickel Ni) with (palladium Pd) with (gold Au)	IBM_TDB USPAT;	2004/07/28 13:25
į			US-PGPUB; EPO; JPO; DERWENT;	-
-	6680	(copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au)	IBM_TDB USPAT;	2004/07/28 13:26
			US-PGPUB; EPO; JPO; DERWENT;	
-	21	((copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au))	IBM_TDB USPAT;	2004/07/28 14:17
		with bond\$3 near3 pad	US-PGPUB; EPO; JPO; DERWENT;	
-	12722	(257/81,89,666-677,779-784).CCLS.	IBM_TDB USPAT;	2004/07/28 14:19
			US-PGPUB; EPO; JPO; DERWENT;	
-	138	((257/81,89,666-677,779-784).CCLS.) and ((copper Cu) near5 (nickel	IBM_TDB USPAT;	2004/07/28 14:19
		Ni) near5 (palladium Pd) near5 (gold Au))	US-PGPUB; EPO; JPO; DERWENT;	
-	2	((copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au))	IBM_TDB USPAT;	2004/07/28 14:20
		with film near3 carrier	US-PGPUB; EPO; JPO;	
			DERWENT; IBM_TDB	

-	17	((copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au))	USPAT;	2004/07/28 14:38
		with lead near3 frame	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
•	0	(((copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au))	USPAT;	2004/07/28 14:40
		with lead near3 frame) and wiring near5 pattern\$3 and insulat\$4 near3	US-PGPUB;	
		film	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	(((copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au))	USPAT;	2004/07/28 14:40
		with lead near3 frame) and wiring and insulat\$4 near3 film	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
	,		IBM_TDB	2004/05/2014 40
-	1	(((copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au))	USPAT;	2004/07/28 14:40
		with lead near3 frame) and wiring and insulat\$4	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1	///257/01 00 666 677 770 704) COLC ) and //aamon Cu) mag-5 (mintral	IBM_TDB USPAT;	2004/07/28 15:28
-	1	(((257/81,89,666-677,779-784).CCLS.) and ((copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au))) and (TAB or (tape near3	USPAT, US-PGPUB;	2004/0//28 13.28
		automate near3 bonding) or (CSP (chip near size near package) cof (chip	EPO; JPO;	
		adj on adj film) BGA (ball near grid near array))) with film near3 carrier	DERWENT;	
	:	adj on adj min) boA (ban near gnd near array))) with min nears carrier	IBM TDB	
_	20	((copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au))	USPAT;	2004/07/28 15:43
_	20	and (TAB or (tape near3 automate near3 bonding) or (CSP (chip near	US-PGPUB;	2004/07/28 13.43
		size near package) cof (chip adj on adj film) BGA (ball near grid near	ЕРО; ЛРО;	
		array))) with film near3 carrier	DERWENT;	
		WARDING THE AND THE AN	IBM TDB	
_	10	(((copper Cu) near5 (nickel Ni) near5 (palladium Pd) near5 (gold Au))	USPAT;	2004/07/28 15:44
		and (TAB or (tape near3 automate near3 bonding) or (CSP (chip near	US-PGPUB:	
		size near package) cof (chip adj on adj film) BGA (ball near grid near	ЕРО; ЛРО;	
		array))) with film near3 carrier) and insulat\$4	DERWENT;	
	1		IBM TDB	